

SURFACE MOUNT RECTIFIER

REVERSE VOLTAGE: 50 --- 1000 V
CURRENT: 1.5 A

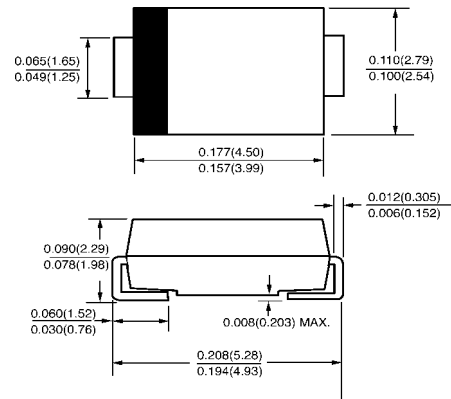
FEATURES

- ◇ Plastic package has underwriters laboratory flammability classification 94V-0
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering:
250°C/10 seconds at terminals

MECHANICAL DATA

- ◇ Case: JEDEC DO-214AC, molded plastic over passivated chip
- ◇ Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026
- ◇ Polarity: Color band denotes cathode end
- ◇ Weight: 0.002 ounces, 0.064 gram

DO - 214AC(SMA)



inch(mm)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		S2AA	S2BA	S2DA	S2GA	S2JA	S2KA	S2MA	UNITS
		SAA	SBA	SDA	SGA	SJA	SKA	SMA	
Device marking code		SAA	SBA	SDA	SGA	SJA	SKA	SMA	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RWS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ $T_L = -90^\circ\text{C}$	$I_{F(AV)}$	1.5							A
Peak forward surge current @ $T_L = 110^\circ\text{C}$ 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A
Maximum Instantaneous forward voltage at 1.5A	V_F	1.15							V
Maximum DC reverse current @ $T_A = 25^\circ\text{C}$	I_R	5.0							μA
at rated DC blocking voltage @ $T_A = 125^\circ\text{C}$		125							
Typical junction capacitance (NOTE 2)	C_J	20							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	50							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J T_{STG}$	-55-----+150							$^\circ\text{C}$

NOTE: 1.Reverse recovery time test conditions: $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25\text{A}$

2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

3. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.27"X0.27" (7.0X7.0mm²) copper pad areas

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FIG.1 – FORWARD DERATING CURVE

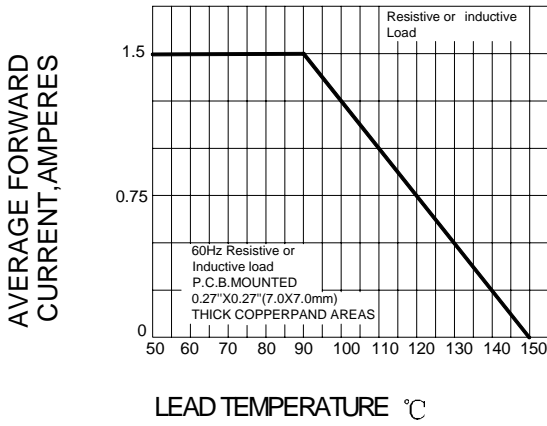


FIG.2 PEAK FORWARD SURGE CURRENT

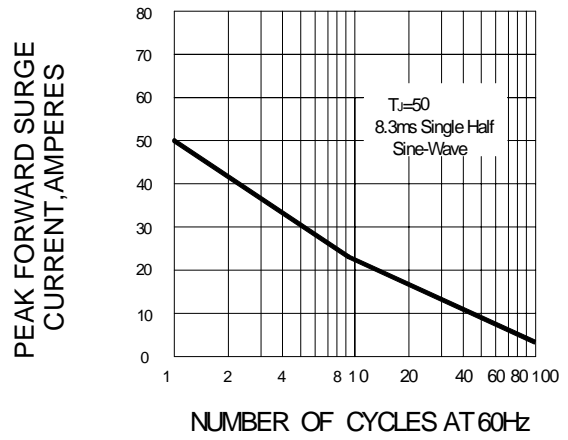


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

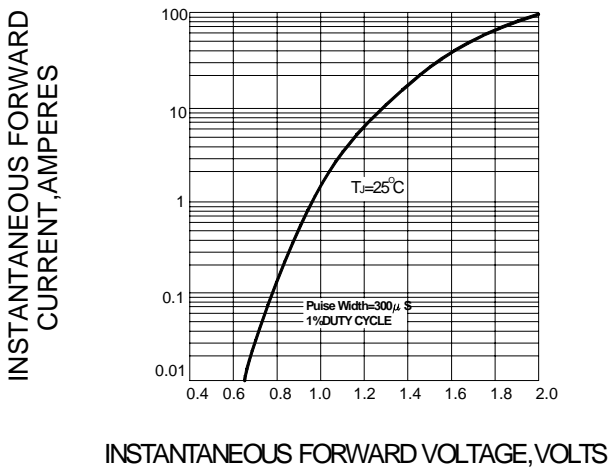


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

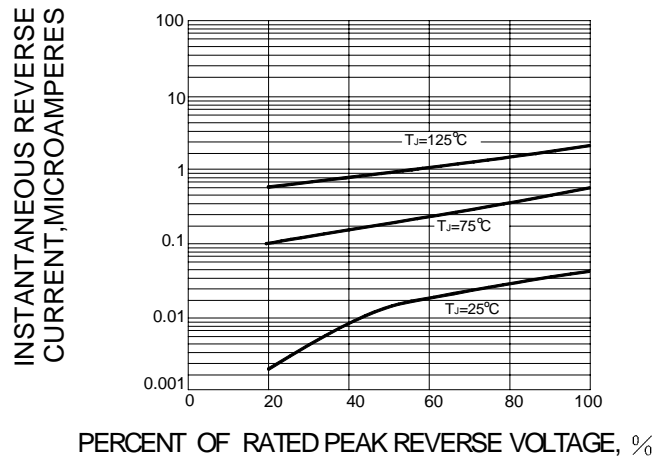


FIG.5-TYPICAL JUNCTION CAPACITANCE

